

Data Sheet

Description

The SPEG-21515 is a 150 V, 15 A Schottky diode with a trench structure, allowing improvements in V_F and I_R characteristics. These characteristic features contribute to improving power supply efficiency and to enabling highfrequency systems.

Features

•	V _{RM} 150 V
•	$I_{F(AV)}$
	$V_F (I_F = 6.5 \text{ A})$ 0.90 V typ
_	Para Load Frame: Dh fran (DoUS Compliant)

- Bare Lead Frame: Pb-free (RoHS Compliant)
- Flammability: Equivalent to UL94V-0
- AEC-Q101 Qualified

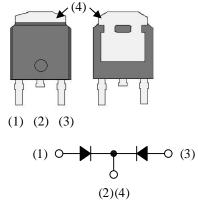
Applications

High speed switching applications as follows:

- DC-DC Converter
- Reverse Protection

Package

TO252-2L



- (1) Anode
- (2) Cathode
- (3) Anode
- (4) Cathode

Not to scale

Absolute Maximum Ratings

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Rating	Unit
Nonrepetitive Peak Reverse Voltage ⁽¹⁾	V _{RSM}		150	V
Repetitive Peak Reverse Voltage ⁽¹⁾	V_{RM}		150	V
Average Forward Current	$I_{F(AV)}$	See Figure 3 and Figure 4	15	A
Surge Forward Current ⁽¹⁾	I_{FSM}	Half cycle sine wave, positive side, 10 ms, 1 shot	90	A
I ² t Limiting Value ⁽¹⁾	I ² t	$1 \text{ ms} \le t \le 10 \text{ ms}$	40.5	A^2s
Junction Temperature	T_{J}		-55 to 150	°C
Storage Temperature	T_{STG}		-55 to 150	°C

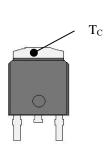
Electrical Characteristics

Unless otherwise specified, $T_A = 25$ °C.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage Drop ⁽¹⁾	V_{F}	$I_F = 6.5 A$		0.90	0.98	V
Reverse Leakage Current ⁽¹⁾	I_R	$V_R = V_{RM}$			70	μΑ
Reverse Leakage Current under High Temperature ⁽¹⁾	$H \cdot I_R$	$V_R = V_{RM}$, $T_J = 150$ °C			35	mA
Thermal Resistance ⁽²⁾	R _{th(J-C)}	(3)			3.5	°C/W

Mechanical Characteristics

Parameter	Conditions	Min.	Тур.	Max.	Unit
Package Weight		_	0.32	_	g



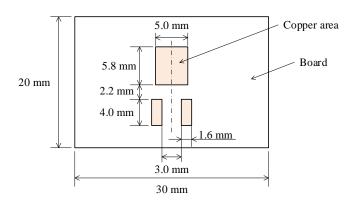


Figure 1. Case Temperature Measurement Point

Figure 2 Glass-epoxy Board

⁽¹⁾ Specifies a value per chip; the SPEG-21515 consists of two chips.

 $^{^{(2)}}$ $R_{th (J-C)}$ is thermal resistance between junction and the case. Case Temperature, T_C , is measured at the point defined in Figure 1.

 $^{^{(3)}}$ The device is mounted on the glass-epoxy board (PCB: 42 mm \times 32 mm in size, 1 mm in thickness, copper area: see Figure 2).

Derating Curves

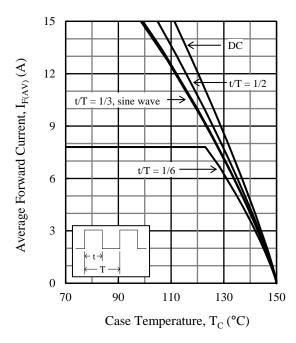


Figure 3. $I_{F(AV)}$ vs. T_C ($T_J = 150$ °C, $V_R = 0$ V)

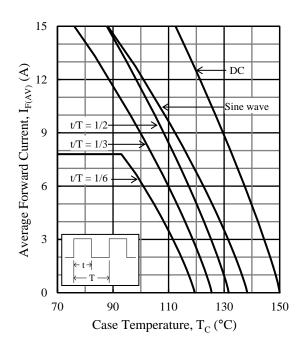


Figure 4. $I_{F(AV)}$ vs. T_C ($T_J = 150$ °C, $V_R = 150$ V)

Characteristic Curves

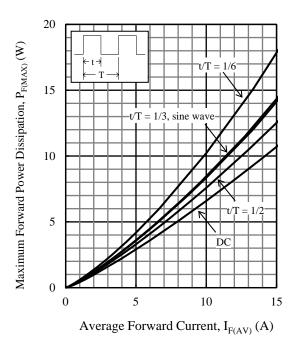


Figure 5. $P_{F(MAX)}$ vs. $I_{F(AV)}$ ($T_J = 150$ °C)

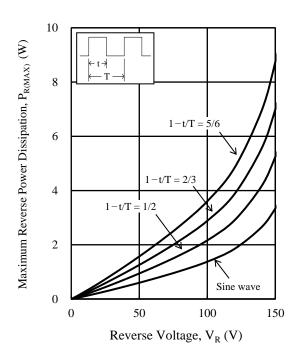
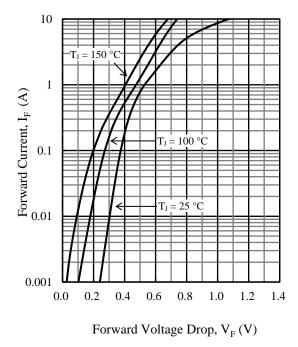


Figure 6. $P_{R(MAX)}$ vs. V_R ($T_J = 150$ °C)



1.E-03

1.E-03

1.E-04

1.E-05

1.E-05

1.E-06

1.E-07

1.E-08

0

50

1.E-08

Reverse Voltage, V_R (V)

Figure 7. Typical Characteristics: I_F vs. V_F

Figure 8. Typical Characteristics: I_R vs. V_R

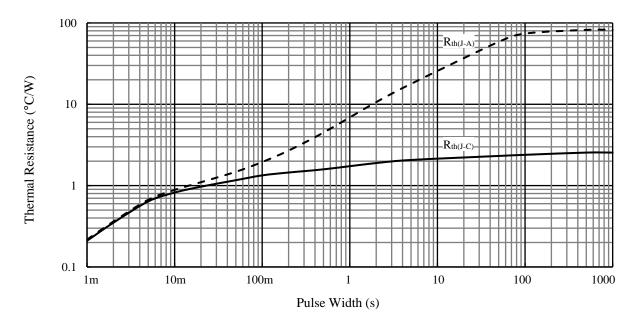
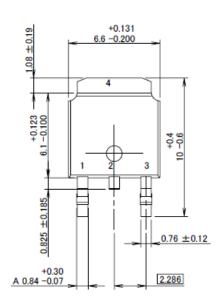
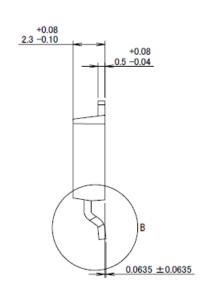


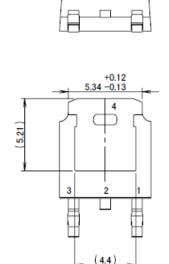
Figure 9. Typical Transient Thermal Resistance Characteristics

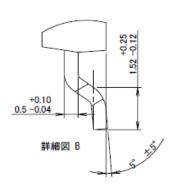
Physical Dimensions

• TO252-2L Package









NOTES:

- Dimensions in millimeters
- All the dimensions exclude mold flashes, protrusions, and gate burrs.
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:

Flow: 260 °C / 10 s, 1 time

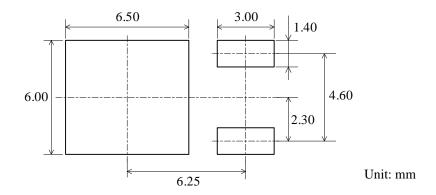
Reflow:

Preheat: 150 °C to 200 °C / 60 s to 120 s

Solder heating: 255 °C / 30 s, 3 times (260 °C peak)

Soldering Iron: 350 °C / 3.5 s, 1 time

• TO252-2L Land Pattern Example



Marking Diagram

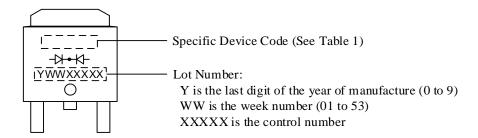


Table 1. Specific Device Code

Specific Device Code	Part Number
EG1515	SPEG-21515

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